

Technical Data Sheet

Schulamid 66/6 MT 20 K1849 NAT

Polyamide 66/6 Copolymer

Product Description

20% talc filled and impact modified Polyamide 66/6

Processing Method Injection Molding

Attribute Good Stiffness; Medium Viscosity; Oil Resistant; Wear Resistant

Filler/Reinforcement Talc, 20%

Typical Properties	Nominal Value	Units	Test Method
Physical			
Density, (Method A)	1.28	g/cm ³	ISO 1183
Mechanical			
Tensile Stress at Yield			
(Type 1A, 50 mm/min)	50.0	MPa	ISO 527-2
(Type 1A, 50 mm/min) - Conditioned	33.0	MPa	ISO 527-2
Tensile Strain at Yield			
(Type 1A, 50 mm/min)	3.5	%	ISO 527-2
(Type 1A, 50 mm/min) - Conditioned	27	%	ISO 527-2
Tensile Modulus			
(1 mm/min, Type 1A)	3700	MPa	ISO 527-1
(1 mm/min, Type 1A) - Conditioned	1500	MPa	ISO 527-1
Impact			
Charpy Impact Strength - Notched			
(23 °C, Type 1, Edgewise, Notch A)	12	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A)	9.0	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise, Notch A) - Conditioned	20	kJ/m ²	ISO 179
Charpy Impact Strength - Unnotched			
(23 °C, Type 1, Edgewise)	No Break		ISO 179
(-30 °C, Type 1, Edgewise)	No Break		ISO 179
(23 °C, Type 1, Edgewise) - Conditioned	No Break		ISO 179
Thermal			
Vicat Softening Temperature			
(B (50N), 50 °C/h)	175	°C	ISO 306
(A (10N), 50 °C/h)	220	°C	ISO 306
Deflection Temperature Under Load Unannealed (0.45 MPa), (Flatwise)	180	°C	ISO 75-2/B
Deflection Temperature Under Load Unannealed (1.80 MPa), (Flatwise)	65.0	°C	ISO 75-2/A
Electrical			

Volume Resistivity	>1.0E+13	ohm*m	IEC 62631-3-1
- Conditioned	>1.0E+10	ohm*m	IEC 62631-3-1
Surface Resistivity	>1.0E+15	ohm	IEC 60093
- Conditioned	>1.0E+12	ohm	IEC 60093

Flammable

Burning Rate			
(2.00 mm)	<100	mm/min	FMVSS 302
(2.00 mm)	<100	mm/min	ISO 3795

Additional Information

Water Absorption 23C/50RH	1.4	%	ISO 62
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UL Information

Flammability Classification			
(1.5 mm)	HB		IEC 60695-11-10, -20
(3.0 mm)	HB		IEC 60695-11-10, -20

Injection Parameters	Nominal Value	Units
Drying Time	2.0 to 4.0	hr
Drying Temperature	80	°C
Suggested Max Moisture	0.040 to 0.10	%
Processing (Melt) Temp	270 to 300	°C
Mold Temperature	70 to 100	°C